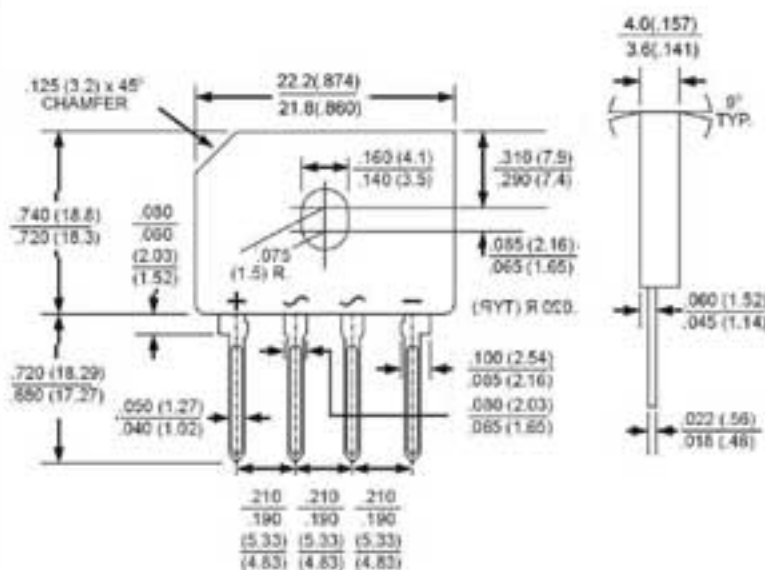


## GLASS PASSIVATED BRIDGE RECTIFIERS

REVERSE VOLTAGE - 50 to 1000 Volts  
FORWARD CURRENT - 10/15/25/35 Amperes

### FEATURES

- Surge overload rating - 200 ~ 400 amperes peak
- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- Plastic material has Underwriters Laboratory Flammability classification 94V-0
- Mounting Position: Any



Dimensions in inches and (millimeters)

### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%

CHARACTERISTICS	SYMBOL	GBU(G)	GBU(G)	GBU(G)	GBU(G)	GBU(G)	GBU(G)	GBU(G)	UNIT
		10005	1001	1002	1004	1006	1008	1010	
		15005	1501	1502	1504	1506	1508	1510	
		25005	2501	2502	2504	2506	2508	2510	
		35005	3501	3502	3504	3506	3508	3510	
Maximum Recurrent Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum Average Forward (with heatsink Note 2) Rectified Current @ $T_C=100^\circ\text{C}$ (without heatsink)	$I_{AV}$	10/15/25/35 3.6							A
Peak Forward Surge Current 10A 8.3ms single half sine-wave 15A super imposed on rated load (JEDEC Method) 25A 35A	$I_{FSM}$	200 220 340 400							A
Maximum Forward Voltage at 5.0/7.5/12.5/17.5A DC	$V_F$	1.1							V
Maximum DC Reverse Current @ $T_J=25^\circ\text{C}$ at Rated DC Blocking Voltage @ $T_J=125^\circ\text{C}$	$I_R$	5.0 500							$\mu\text{A}$
$I^2t$ Rating for fusing ( $t < 8.3\text{ms}$ )	$I^2t$	200							$\text{A}^2\text{S}$
Typical Junction Capacitance per element (Note 1)	$C_J$	70							pF
Typical Thermal Resistance (Note 2)	$R_{\theta JC}$	2.2							$^\circ\text{C/W}$
Operating Temperature Range	$T_J$	-55 to +150							$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 to +150							$^\circ\text{C}$

NOTES: 1. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.  
2. Device mounted on 100mm x 100mm x 1.6mm Cu Plate Heatsink.